



US00D346154S

# United States Patent [19]

[11] Patent Number: **Des. 346,154**

Alden et al.

[45] Date of Patent: **\*\* Apr. 19, 1994**

[54] **ORNAMENTAL DESIGN FOR A CIRCUIT PACK FACEPLATE**

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[57] **CLAIM**

The ornamental design for a circuit pack faceplate, as shown and described.

[73] Assignee: **AT&T Bell Laboratories, Murray Hill, N.J.**

### DESCRIPTION

[\*\*] Term: **14 Years**

FIG. 1 is a front view of a circuit pack faceplate in accordance with the embodiment of the design; FIG. 2 is a side view thereof; FIG. 3 is a view of the side opposite to that shown in FIG. 2;

[21] Appl. No.: **807,383**

FIG. 4 is a rear view thereof;

[22] Filed: **Dec. 16, 1991**

FIG. 5 is a top view thereof;

[52] U.S. Cl. .... **D13/177**

FIG. 6 is a bottom view thereof;

[58] Field of Search ..... **D8/353; 361/331, 380, 361/392, 394, 413, 417; D13/162, 163, 168, 177**

FIG. 7 is a perspective view thereof;

FIG. 8 is a front view of a circuit pack faceplate in accordance with the second embodiment of the design; and,

### [56] References Cited

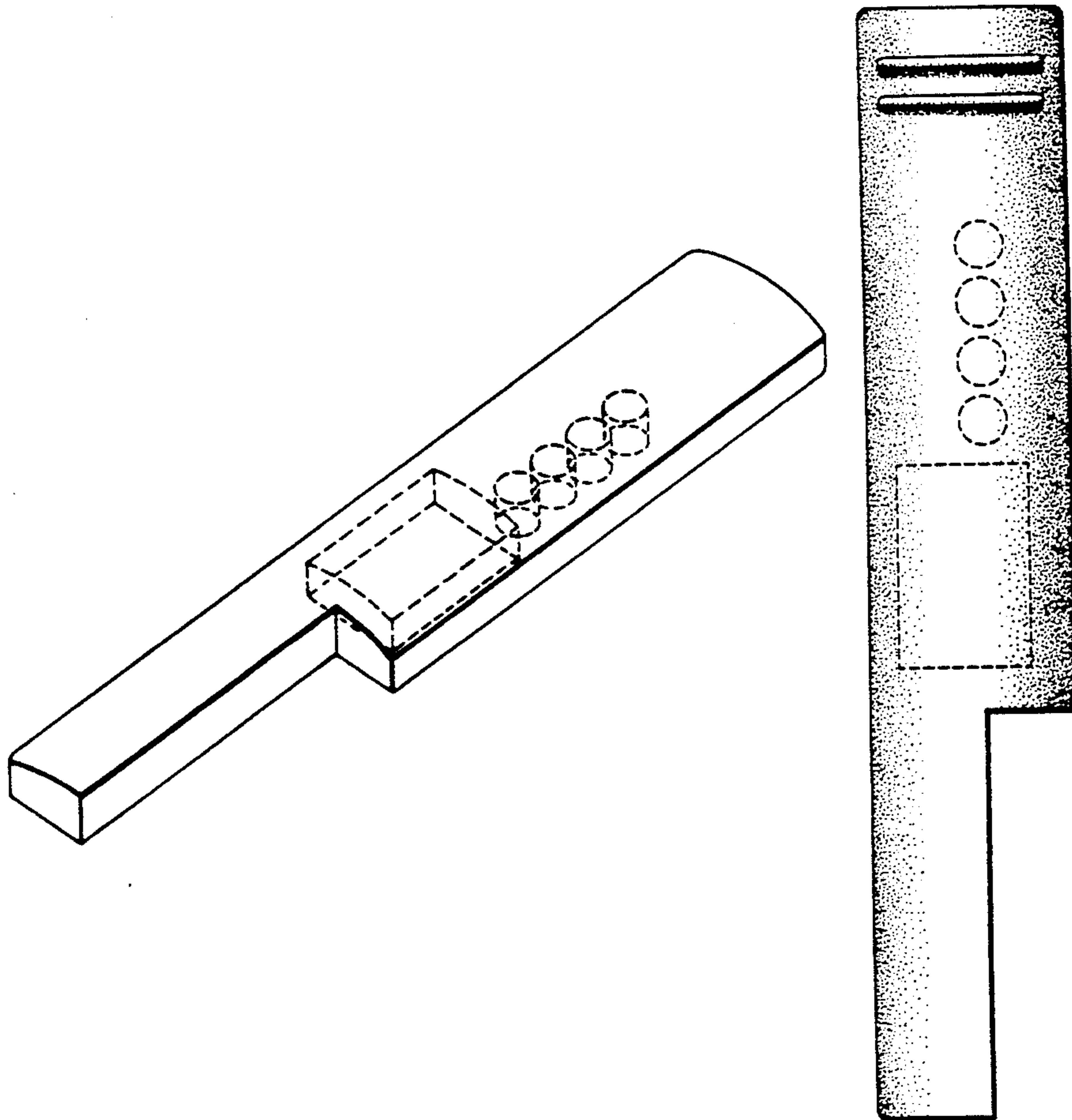
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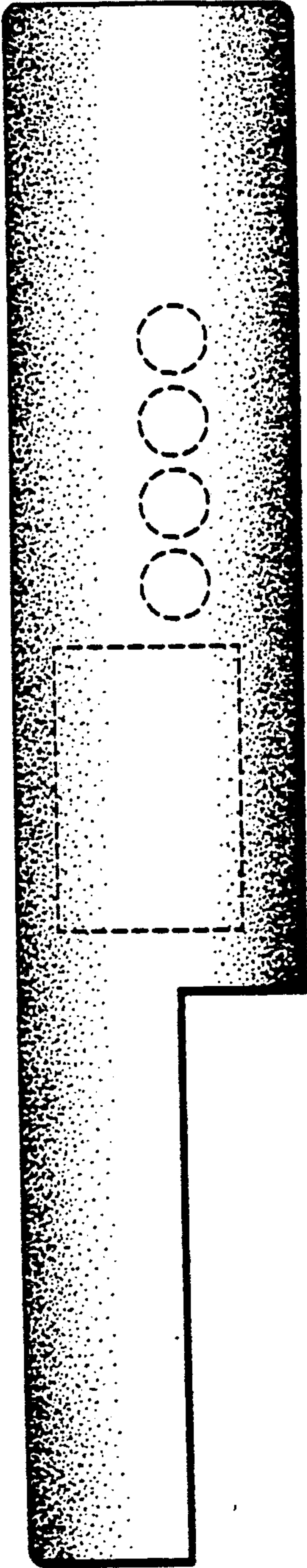
FIG. 9 is a side view thereof, all other views are the same as the first embodiment except for the presence of the two ribs at the top of the front.

The broken line showing throughout the drawing figures is included for the purpose of illustrating environmental elements only and forms no part of the claimed design.

*Primary Examiner*—Wallace R. Burke  
*Assistant Examiner*—Joel Sincavage



*FIG. 1*



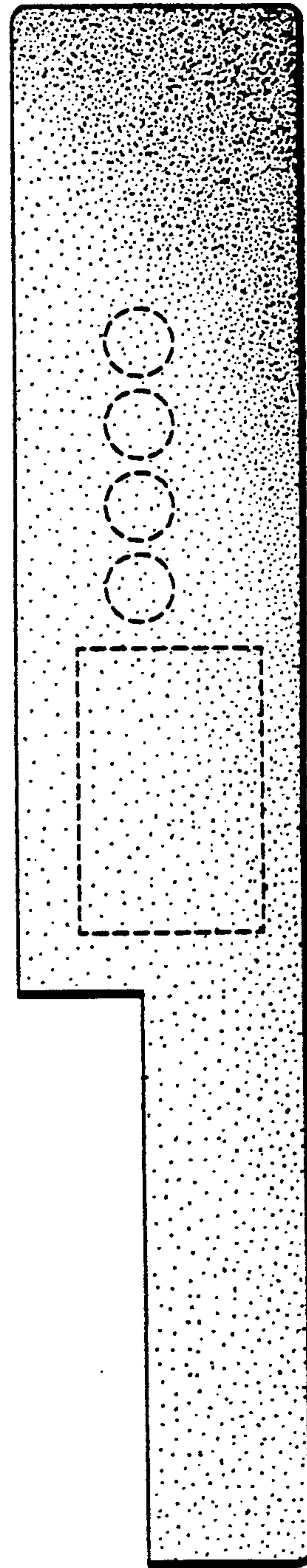
*FIG. 2*



*FIG. 3*



*FIG. 4*



*FIG. 5*



*FIG. 6*



*FIG. 7*

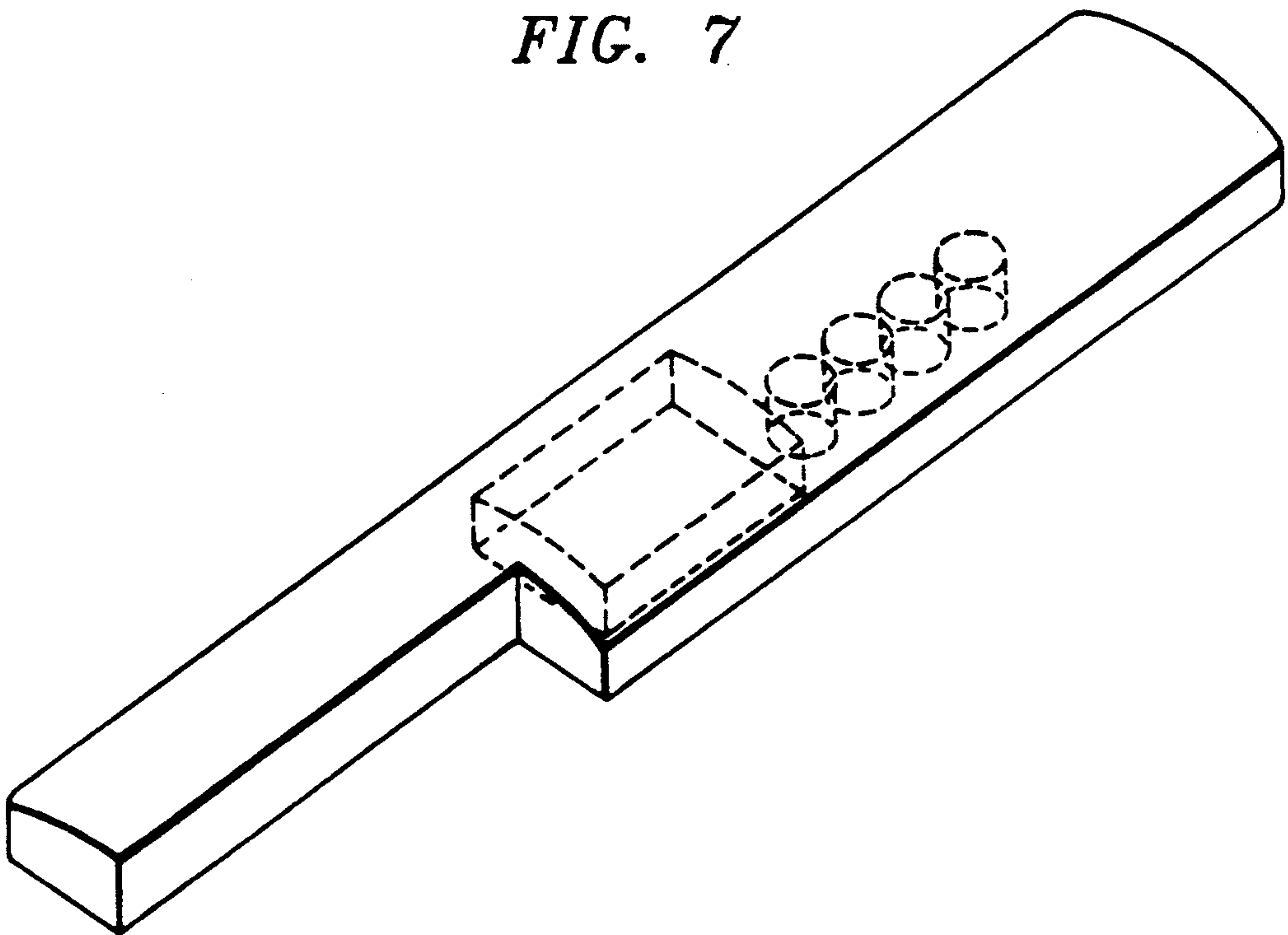




FIG. 8

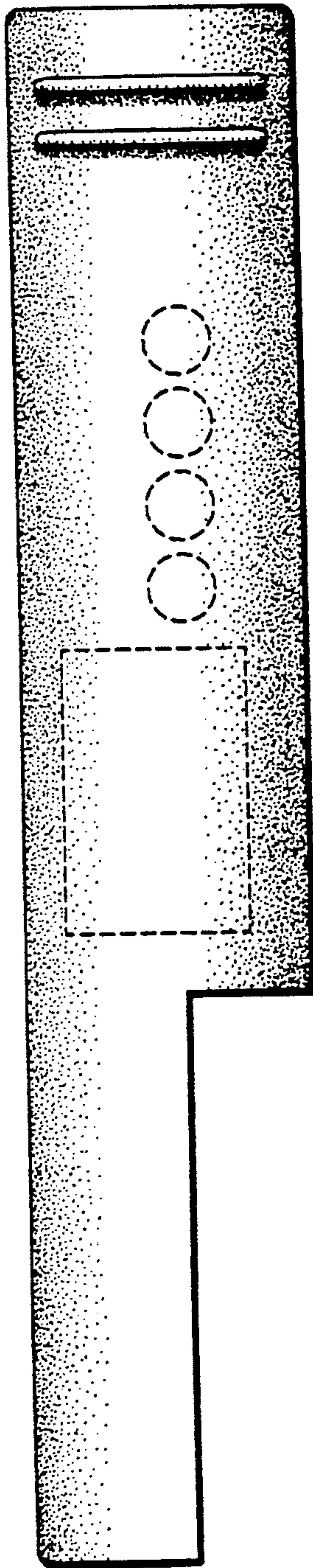


FIG. 9

